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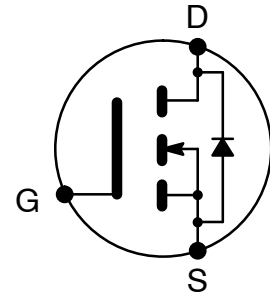
## NTE2950 MOSFET N-Channel, Enhancement Mode High Speed Switch TO-262 Type Package

**Features:**

- Low  $R_{DS(ON)}$  Reduces Losses
- Low Gate Charge Improves the Switching Performance
- Improved Diode Recovery Improves Switching & EMI Performance
- 30V Gate Voltage Rating Improves Robustness
- Fully Characterized Avalanche SOA

**Applications**

- Motion Control Applications
- High Efficiency Synchronous Rectification in SMPS
- Uninterruptible Power Supply
- Hard Switched and High Frequency Circuits



**Absolute Maximum Ratings:**

Continuous Drain Current ( $V_{GS} = 10V$ ), $I_D$	
$T_C = +25^\circ C$ (Note 1)	85A
$T_C = +100^\circ C$	60A
Pulsed Drain Current (Note 2), $I_{DM}$	330A
Maximum Power Dissipation ( $T_C = +25^\circ C$ ), $P_D$	350W
Linear Derating Factor	2.3W/ $^\circ C$
Gate-to-Source Voltage, $V_{GS}$	$\pm 30V$
Single Pulse Avalanche Energy (Thermally Limited, Note 3), $E_{AS}$	120mJ
Operating Junction Temperature Range, $T_{opr}$	$-55^\circ$ to $+175^\circ C$
Storage Temperature Range, $T_{STG}$	$-55^\circ$ to $+175^\circ C$
Lead Temperature (During soldering, 10 sec. max, 1.6mm from case), $T_L$	$+300^\circ C$
Thermal Resistance, Junction-to-Case (Note 4, Note 5), $R_{thJC}$	0.43 $^\circ C/W$
Thermal Resistance, Junction-to-Ambient (Note 4), $R_{thJA}$	40 $^\circ C/W$

Note 1. Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 75A

Note 2. Repetitive rating: pulse width limited by max. junction temperature.

Note 3. Limited by  $T_{Jmax}$ , starting  $T_J = +25^\circ C$ ,  $L = 0.096mH$ ,  $R_G = 25\Omega$ ,  $I_{AS} = 50A$ ,  $V_{GS} = 10V$ . Device not recommended for use above this value.

Note 4. Thermal resistance is measured at  $T_J$  approximately  $+90^\circ C$ .

Note 5.  $R_{thJC}$  (end of life) = 0.65 $^\circ C/W$ . This is the maximum measured value after 1000 temperature cycles from  $-55^\circ$  to  $+15^\circ C$  and is accounted for by the physical wearout of the die attach medium.



## Electrical Characteristics:

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Static</b> ( $T_J = +25^\circ\text{C}$ unless otherwise specified)						
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	150	–	–	V
Breakdown Voltage Temp. Coefficient	$\Delta V_{(BR)DSS} / \Delta T_J$	Reference to $+25^\circ\text{C}$ , $I_D = 1\text{mA}$ , Note 2	–	150	–	mV/ $^\circ\text{C}$
Static Drain-to-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 33A$ , Note 6	–	12	15	m $\Omega$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	3.0	–	5.0	V
Drain-to-Source Leakage Current	$I_{DSS}$	$V_{DS} = 150V,$ $V_{GS} = 0V$	–	–	20	$\mu\text{A}$
			$T_J = +125^\circ\text{C}$	–	–	1.0
Gate-to-Source Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V$	–	–	$\pm 100$	nA
Internal Gate Resistance	$R_{G(int)}$		–	0.8	–	$\Omega$
<b>Dynamic</b> ( $T_J = +25^\circ\text{C}$ unless otherwise specified)						
Forward Transconductance	$g_{fs}$	$V_{DS} = 25V, I_D = 50A$	130	–	–	S
Total Gate Charge	$Q_g$	$I_D = 50A, V_{DS} = 75V,$ $V_{GS} = 10V$ , Note 6	–	71	110	nC
Gate-to-Source Charge	$Q_{gs}$		–	24	–	nC
Gate-to-Drain (“Miller”) Charge	$Q_{gd}$		–	21	–	nC
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 98V, I_D = 50A, R_G = 2.5\Omega,$ $V_{GS} = 10V$ , Note 6	–	18	–	ns
Rise Time	$t_r$		–	60	–	ns
Turn-Off Delay Time	$t_{d(off)}$		–	25	–	ns
Fall Time	$t_f$		–	35	–	ns
Input Capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = 50V, f = 1\text{MHz}$	–	4460	–	pF
Output Capacitance	$C_{oss}$		–	390	–	pF
Reverse Transfer Capacitance	$C_{rss}$		–	82	–	pF
<b>Diode Characteristics</b>						
Continuous Source Current (Body Diode)	$I_S$	Note 1	–	–	85	A
Pulsed Source Current (Body Diode)	$I_{SM}$	Note 2	–	–	330	A
Diode Forward Voltage	$V_{SD}$	$I_S = 50A, V_{GS} = 0V, T_J = +25^\circ\text{C}$ , Note 6	–	–	1.3	V
Reverse Recovery Time	$t_{rr}$	$I_D = 50A, V_R = 128V,$ $di/dt = 100A/\mu\text{s}$ , Note 6	–	89	130	ns
Reverse Recovery Charge	$Q_{rr}$		–	300	450	nC
Reverse Recovery Current	$I_{RRM}$		–	6.5	–	A
Forward Turn-On Time	$t_{on}$	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Note 1. Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 75A

Note 2. Repetitive rating: pulse width limited by max. junction temperature.

Note 6. Pulse width  $\leq 400\mu\text{s}$ ; duty cycle  $\leq 2\%$ .

